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	Designed for: Public Release	se Mod. D	ate: 10/5/2017	
79	Project Title: Load_Transient			TEXAS
Rev: A	Project Title: Load_Transient Sheet Title: INSTRUMENTS			
ontrol disabled	Assembly Variant: 001		Sheet:1 of 2	II (STICOME) (15
ara Diop	File: TIDA-01379_Load_Tr	ansient_A.SchDoc	Size: B	http://www.ti.com
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PCB Number: TIDA-01379 PCB Rev: A

PCB LÓGO Texas Instruments



PCB LOGO Texas Instruments PCB LOGO Pb-Free Symbol

PCB LOGO PCB LÕĜO Texas Instruments Pb-Free Symbol

LBL1 PCB Label

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Size: 0.65" x 0.20 "

LBL2 PCB Label Size: 0.65" x 0.20 "

ZZ1
Label Assembly Note
This Assembly Note is for PCB labels only

Variant/Label Table		
Variant	Label Text	
001	ChangeMe!	
002	ChangeMe!	

ZZ2
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

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ZZ4 Assembly Note These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

 Orderable:
 N/A
 Designed for: Public Release
 Mod. Date: 6/23/2017

 TID #:
 TIDA-01379
 Project Title: Load_Transient

 Number:
 TIDA-01379
 Rev: A
 Sheet Title:

 Variant: that this design will meet the specifications, will be suitable for your application or fit for any particular purpose, or will operate in an implementation. Texas Instruments and/or its licensors do not warrant that the design is production worthy. You should completely validate and test your design implementation to confirm the system functionality for your application.
 SVN Rev:
 Version control disabled
 Sheet: 2 of 2

 Drawn By:Sokhna Diaara Diop
 File: TIDA-01379
 Load_Transient A_Hardware.Sch/Diaze: B
 Engineer: Sokhna Diaara Diop
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